

UNAPPROVED MINUTES

IEEE 802.3 Ethernet Working Group

Plenary Opening Meeting

10-Nov 2025

<https://www.ieee802.org/3/minutes/nov25/index.html>

MONDAY, 10-NOV 2025

Minutes were taken by IEEE recording secretary Jon Lewis.

ADMINISTRATIVE MATTERS

Call to order

Adam Healey, Vice-Chair of the IEEE 802.3 Ethernet Working Group, called the meeting to order at 10:15 ICT.

Welcome, introductions, and general announcements

Mr. Healey noted that it would be too time consuming to have each individual introduce themselves, that introductions would not be done at this hybrid meeting.

Mr. Healey showed a list of officers of the IEEE 802.3 Working Group:

IEEE 802.3 Chair: David Law

IEEE 802.3 Vice-Chair: Adam Healey

IEEE 802.3 Secretary: Jon Lewis

IEEE 802.3 Executive Secretary: Chad Jones

IEEE 802.3 Treasurer: Valerie Maguire

IEEE 802.3 Task Force chairs

IEEE P802.3da 10SPE Multidrop Enhancements: Chad Jones

IEEE P802.3dg 100 Mb/s Long-Reach Single Pair Ethernet Task Force: George Zimmerman

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet: John D'Ambrosia

IEEE P802.3dk Greater than 50 Gb/s Bidirectional Optical Access PHYs: Yuanqiu Luo

IEEE P802.3dm Asymmetrical Electrical Automotive Ethernet: Natalie Wienckowski

IEEE P802.3dp Cabling Restrictions for Single Pair Power over Ethernet: Chad Jones

IEEE P802.3dq Pin-Optimized PHY Interface: Jason Potterf

IEEE Std 802.3-2022/Cor 2 (IEEE 802.3dr) Optical Automotive Ethernet TDFOM: Luisma Torres

IEEE 802.3 Study Group chair

IEEE 802.3 200 Gb/s per Wavelength MMF PHYs Study Group: Mabud Choudhury

IEEE 802.3 Ethernet Metadata Services Study Group: David Ofelt

IEEE 802.3 Task Force vice-chairs

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet: Mark Nowell

Working Group Decorum

Mr. Healey introduced the Working Group decorum as described in the opening report. Please see https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=3 .

Mr. Healey noted that there should be no recording without permission and that recording was disabled for this meeting in the teleconference tool.

Mr. Healey asked if anyone was attending from the press including those who would run a public blog on this meeting other than those limited to summarizing the meeting. There was no response.

Mr. Healey introduced the procedure for participants including their affiliation in their screen name and noted other zoom guidelines for in-person and remote participants including the operation of the queues. Please see

https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=6 .

Mr. Healey informed the group that the November plenary meeting is subject to a registration fee and that there are penalties for non-payment of registration fees.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=8 .

Review and approval of agenda

Mr. Healey noted that a soft copy of the draft agenda had been posted to the minutes section for this meeting.

Mr. Healey asked if there were any modifications to the draft agenda. It was noted that Marek would present the 802.3.2 agenda item instead of Ulf.

MOTION #1

Approve the agenda as posted.

M: K. Lusted

S: M. Dudek

Procedural (> 50%)

Motion Passed by unanimous consent 10-Nov 2025, 10:25 a.m. ICT

MOTION #2

Approve the July 2025 plenary and September 2025 interim minutes as posted.

M: K. Lusted

S: J. Weaver

Procedural (> 50%)

Motion Passed by unanimous consent 10-Nov 2025, 10:27 a.m. ICT

Call for patents

Please see:

https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=12

Mr. Healey showed the IEEE patent policy slides.

Mr. Healey asked if anyone was aware of any patent claims potentially essential to the proposed standards under development by the IEEE 802.3 Working Group. There was no response.

Mr. Healey asked that Mr. Lewis record that:

The patent policy, per the latest PatCom slide set, was shown

There was no response to the call for potentially essential patent claims

Anyone wishing to submit a letter of assurance can do so at any time by contacting Mr. Law or the PatCom administrator

Mr. Healey reminded the group of inappropriate topics that should not be discussed. These included territory, market share, price, ongoing litigation, threatened litigation, etc.

Mr. Healey reviewed the IEEE SA copyright slides.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=17

Mr. Healey advised participants that:

- IEEE SA's copyright policy is described in Clause 7 of the IEEE SA Standards Board Bylaws and Clause 6.1 of the IEEE SA Standards Board Operations Manual;
- Prior to presentation or submission, you shall notify the Working Group Chair of previously Published material and should assist the Chair in obtaining copyright permission acceptable to IEEE SA. For material that is not previously Published, IEEE is automatically granted a license to use any material that is presented or submitted.

Mr. Healey reviewed the IEEE SA participation slides.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=19

Mr. Healey advised participants that:

- Participants in the IEEE-SA "individual process" under which the project operates shall act independently of others, including employers, and shall act based on their qualifications and experience. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation.

General Working Group business

Mr. Healey explained the membership requirements (gaining):

- Attendance in at least 75% of meeting slots¹ at 2 of the last 4 plenary sessions
 - Attendance in at least 75% of meeting slots at recent IEEE 802.3 Ethernet Working Group or Task Group Interim Session may be substituted for one of the two Plenary Sessions

¹ There are four IMAT meeting slots during the day during plenary and credited interim sessions

- Attendance in at least 75% of the meeting slot's duration is required for that attendance to count towards gaining or maintaining voting membership
- Maintain valid contact information
- Consistent declaration of affiliation
- Request to become member during potential voter agenda item at an IEEE 802.3 Ethernet Working Group opening or closing **plenary** meeting

Membership requirements (retaining)

- Continue to meet above attendance, contact, and affiliation requirements
- Participate in two out of the last three Working Group Letter Ballot Series

Mr. Lewis reviewed the membership and attendance tool procedures.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=25

Please see <http://ieee802.org/3/rules/index.html> for complete information.

Mr. Healey asked the group to take a moment and sign in to IMAT.

Review of voting membership

Please https://www.ieee802.org/3/minutes/nov25/1125_voters.pdf

Review of voters in peril

Please https://www.ieee802.org/3/minutes/nov25/1125_peril.pdf

Review of Potential voters

Please see https://www.ieee802.org/3/minutes/nov25/1125_potential.pdf

The following participants requested voting rights during the opening plenary:

Fan, Xiaojie	Kutscher, Noam	Seth, Sumantra
George, John	Lim, Hoei	Spruit, Hans
Gupta, Ajeya	Mascitto, Marco	Sriram, Chandrasekhar
Hutchison, Guy	Miskho, Michael	Tu, Mike
Jeffreis, Brad	Muma, Scott	Wu, Dance
Kato, Takahiro	Regev, Alon	Xu, Li
Kim, Do Kyun	Reinhard, Michael	Xu, Wenxiong
Kim, Gyudong	Schedl, Anton	

Mr. Lewis displayed a list of the voters that requested voting rights in the opening plenary. Mr. Healey asked if any new voter that had requested voting rights and were not shown correctly. There was no response.

Mr. Law assumed running the meeting.

Val Maguire presented the Working Group treasury report. Please see

https://www.ieee802.org/3/minutes/nov25/1125_treasury.pdf

Mr. Law showed the IEEE 802 LMSC report and meeting schedule. Please see

https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=31

Mr. Law introduced the In-Person Collaboration being considered at the LMSC and noted that there would be discussing this topic at the closing plenary meeting on Thursday.

Mr. Law showed the instructions for accessing the IEEE 802 eMedia.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=33

Mr. Law showed the other IEEE 802 LMSC PARs under consideration at the plenary session.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_opening_plenary.pdf#page=35

Mr. Lusted reported the outcome of the IEEE 802.3 PAR Ad Hoc that he chaired before the plenary session. He noted that he had then circulated the proposed IEEE 802.3 comments to the IEEE 802.3 dialog reflector, received no suggested changes by the deadline, and submitted the IEEE 802.3 PAR comments to the IEEE 802 LMSC reflector.

LIAISONS

External Liaison letters (new)

ITU-T SG15 Updates to ANT and HNT Standards Overviews and Work Plans [liaison letter](#)

ITU-T SG15 Update to OTNT Standards Overview and Work Plan [liaison letter](#) and [attachment](#)

ITU-T SG15 Development of weakly-coupled multi-core fibre Recommendations [liaison letter](#)

ITU-T SG15 ETCC, 800G in G.698.2 and new B1T applications [liaison letter](#) and attachment [1](#) and [2](#)

ITU-T SG15 Ethernet Metadata Services (EMS) Study Group [liaison letter](#)

ITU-T SG15 Initiation of approval process for draft revised ITU-T G.8020.3 [liaison letter](#)

ITU-T SG15 Consent of draft Recommendation ITU-T G.8020.3 Ed 2.0 [liaison letter](#) and [attachment](#)

ITU-T SG15 IM/DM modelling coordination [liaison letter](#)

ITU-T SG15 Approval of Technical Report on International Optical Networks towards 2030

(ION-2030) and Beyond [liaison letter](#) and [attachment](#)

ITU-T SG15 Technical report of use cases and requirements beyond 10Gbps [liaison letter](#)

OIF: Next Generation CEI-448G Framework document project [liaison letter](#) and [attachment](#)

External Liaison reports

There was no update on ISO/IEC SC25/WG3.

Tom Huber noted that there was no official report and that David Law had mentioned the highlights already.

TIA TR-42 Telecommunications Cabling Systems – George Zimmerman

https://www.ieee802.org/3/minutes/nov25/20251110_TIA_Liaison_Report_802.3.pdf

Opening reports:

IEEE 802.3 rules report – Adam Healey

https://www.ieee802.org/3/minutes/nov25/1125_rules_open_report.pdf

Mr. Law asked if there was anyone that still hadn't signed into IMAT and that he would not be adjusting the attendance after the meeting, none responded.

Mr. Law noted that there were 3 changes necessary to the approved agenda:

- POPI Study Group should be P802.3dq
- The agenda does not show the Ethernet Metadata Services Study Group
- The agenda does not show the 200 Gb/s per wavelength Multimode Fibre (MMF) Study Group

Mr. Law asked if there was any objection to modifying the agenda accordingly, none responded and the agenda was amended.

IEEE 802.3 Maintenance - Adam Healey

https://www.ieee802.org/3/minutes/nov25/1125_maint_open_report.pdf

IEEE P802.3da 10 Mb/s Single Pair Multidrop Segments Enhancement Task Force - Chad Jones

https://www.ieee802.org/3/minutes/nov25/802d3da_task_force_open_report_1125.pdf

IEEE P802.3dg 100 Mb/s Long-Reach Single Pair Ethernet Task Force - George Zimmerman

https://www.ieee802.org/3/minutes/nov25/802d3dg_open_report_Nov2025.pdf

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force - John D'Ambrosia

https://www.ieee802.org/3/minutes/nov25/2511_3dj_open_report.pdf

IEEE P802.3dk Greater than 50 Gb/s Bidirectional Optical Access PHYs Task Force -Yuanqiu Luo

https://www.ieee802.org/3/minutes/nov25/802d3dk_Task_Force_open_report_2025NovPlenary.pdf

IEEE P802.3dm Asymmetrical Electrical Automotive Ethernet Task Force – Natalie Wienckowski

https://www.ieee802.org/3/minutes/nov25/1125_802d3dm_TF_open_report.pdf

IEEE P802.3dp Cabling Restrictions for Single Pair Power over Ethernet Task Force – Chad Jones

https://www.ieee802.org/3/minutes/nov25/802d3dp_task_force_open_report_1125.pdf

IEEE P802.3dq Pin-Optimized PHY Interface Task Force Report – Jason Potterf

https://www.ieee802.org/3/minutes/nov25/POPI_Plenary_Opening_Report_2025-11-10.pdf

IEEE P802.3-2022/Cor 2 (IEEE 802.3dr) Optical Automotive Ethernet TDFOM – Luisma Torres

https://www.ieee802.org/3/minutes/nov25/802d3dr_task_force_open_report_01_1125.pdf

IEEE 802.3 200 Gb/s per wavelength Multimode Fibre (MMF) optical PHYs Study Group opening report – Mabud Choudhury

https://www.ieee802.org/3/minutes/nov25/802d3_open_study_group_report_200GMMF_2511.pdf

IEEE 802.3 Ethernet Metadata Services Study Group opening report – David Ofelt

<https://www.ieee802.org/3/minutes/nov25/2025-11-ems-plenary-opening-report-v2.pdf>

IEEE 802.3 New Ethernet Applications Ad Hoc – Jon Lewis

https://www.ieee802.org/3/minutes/nov25/1125_NEA_open_report.pdf

IEEE 802.3 Power Delivery Coordinating Committee Ad Hoc - Chad Jones

https://www.ieee802.org/3/minutes/nov25/PDCC_adhoc_open_report_1125.pdf

IEEE 802.3 Channel Operating margin (COM) opening report – Howard Heck

https://www.ieee802.org/3/minutes/nov25/1125_COM_ad_hoc_open_report.pdf

IEEE 802.3 YANG Ad Hoc – Peter Jones

https://www.ieee802.org/3/minutes/nov25/802d3_yang_os_adhoc_open_november2025.pdf

Room assignments and Subgroup schedules. Mr. Jones shared how to find the meeting room locations for the week and gave the location on the website for the online schedule.

Mr. Law announced that as the agenda had been exhausted the meeting was adjourned.

Mr. Law adjourned the meeting at 12:09 ICT.

Adjourned.

UNAPPROVED MINUTES

IEEE 802.3 Ethernet Working Group

Plenary Closing Meeting

14-Nov 2025

<https://www.ieee802.org/3/minutes/nov25/index.html>

THURSDAY, 14-NOV 2025

Minutes were taken by IEEE 802.3 Ethernet Working Group Secretary Jon Lewis.

ADMINISTRATIVE MATTERS

Call to order

David Law, Chair of the IEEE 802.3 Ethernet Working Group, called the meeting to order at 13:17 ICT.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf

Welcome, introductions, and general announcements

Mr. Law noted that it would be too time consuming to have each individual introduce themselves, that introductions would not be done at this hybrid meeting.

Mr. Law showed a list of officers of the IEEE 802.3 Working Group:

IEEE 802.3 Chair: David Law

IEEE 802.3 Vice-Chair: Adam Healey

IEEE 802.3 Secretary: Jon Lewis

IEEE 802.3 Executive Secretary: Chad Jones

IEEE 802.3 Treasurer: Valerie Maguire

IEEE 802.3 Task Force chairs

IEEE P802.3da 10SPE Multidrop Enhancements: Chad Jones

IEEE P802.3dg 100 Mb/s Long-Reach Single Pair Ethernet Task Force: George Zimmerman

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet: John D'Ambrosia

IEEE P802.3dk Greater than 50 Gb/s Bidirectional Optical Access PHYs: Yuanqiu Luo

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IEEE P802.3dp Cabling Restrictions for Single Pair Power over Ethernet: Chad Jones

IEEE P802.3dq Pin-Optimized PHY Interface: Jason Potterf

IEEE Std 802.3-2022/Cor 2 (IEEE 802.3dr) Optical Automotive Ethernet TDFOM: Luisma Torres

IEEE 802.3 Study Group chair

IEEE 802.3 200 Gb/s per Wavelength MMF PHYs Study Group: Mabud Choudhury

IEEE 802.3 Ethernet Metadata Services Study Group: David Ofelt

IEEE 802.3 Task Force vice-chairs

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet: Mark Nowell

Working Group Decorum

Mr. Law introduced the Working Group decorum as described in the opening report. Please see https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=3.

Mr. Law noted that there should be no recording without permission and that recording was disabled for this meeting in the teleconference tool.

Mr. Law asked if anyone was attending from the press including those who would run a public blog on this meeting other than those limited to summarizing the meeting. There was no response.

Mr. Law introduced the procedure for participants to provide their affiliation in their screen name and noted other zoom guidelines for in-person and remote participants including the operation of the queues. Mr. Jones notified the group that if this isn't complied with you will be removed from the meeting.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=6.

Mr. Law informed the group that the November plenary meeting is subject to a registration fee and that there are penalties for non-payment of registration fees.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=8 .

Review and approval of agenda

Mr. Law noted that a soft copy of the draft agenda had been posted to the minutes section for this meeting.

Mr. Law asked if there were any additions to the draft agenda. There was no response.

MOTION #1

Approve the agenda modifying the posted agenda as posted.

M: John D'Ambrosia

S: Kent Lusted

Procedural (> 50%)

Motion Passed by unanimous consent 14-Nov 2025, 13:24 ICT

Call for patents

Please see

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=11

Mr. Law showed the IEEE patent policy slides.

Mr. Law asked if anyone was aware of any patent claims potentially essential to the proposed standards under development by the IEEE 802.3 Working Group. There was no response.

Mr. Law asked that Mr. Lewis record that:

The patent policy, per the latest PatCom slide set, was shown

There was no response to the call for potentially essential patent claims

Anyone wishing to submit a letter of assurance can do so at any time by contacting Mr. Law or the PatCom administrator

Mr. Law reminded the group of inappropriate topics that should not be discussed. These included territory, market share, price, ongoing litigation, threatened litigation, etc.

Mr. Law reviewed the IEEE SA copyright slides.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=16

Mr. Law advised participants that:

- IEEE SA's copyright policy is described in Clause 7 of the IEEE SA Standards Board Bylaws and Clause 6.1 of the IEEE SA Standards Board Operations Manual;
- Prior to presentation or submission, you shall notify the Working Group Chair of previously Published material and should assist the Chair in obtaining copyright permission acceptable to IEEE SA. For material that is not previously Published, IEEE is automatically granted a license to use any material that is presented or submitted.

Mr. Law reviewed the Code of Conduct and Code of Ethics at the request of a participant.

Mr. Law reviewed the IEEE SA participation slides.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=19

Mr. Law advised participants that:

- Participants in the IEEE-SA "individual process" under which the project operates shall act independently of others, including employers, and shall act based on their qualifications and experience. By participating in standards activities using the "individual process", you are deemed to accept these requirements; if you are unable to satisfy these requirements then you shall immediately cease any participation.

Mr. Law provided details on specifying your employer and affiliation during IEEE-SA "individual process" meetings.

General Working Group business

Attendance procedures, tool, and e-mail list maintenance

Mr. Law explained the membership requirements (gaining):

- Attendance in at least 75% of meeting slots² at 2 of last 4 plenary sessions

² There are four IMAT meeting slots during the day during plenary and credited interim sessions

- Attendance in at least 75% of meeting slots at a recent IEEE 802.3 Ethernet Working Group or Task Group Interim Session may be substituted for one of the two plenary sessions
- Attendance in at least 75% of meeting slot's duration is required for that attendance to count towards gaining or maintaining voting membership
- Provide valid contact information
- Provide declaration of affiliation
- Request to become member during potential voter agenda item at an IEEE 802.3 Ethernet Working Group opening or closing **plenary** meeting

Membership requirements (retaining)

- Continue to meet the above attendance, contact, and affiliation requirements
- Participate in two out of the last three Working Group Letter Ballot Series

Mr. Law noted the meeting this plenary meeting requires a paid registration fee and that attending any of the sessions without paying the fee had adverse consequences.

Membership and attendance recording

Mr. Lewis reviewed the membership and attendance tool procedures.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=25

Please see <http://ieee802.org/3/rules/index.html> for complete information.

Review of voting membership

Please https://www.ieee802.org/3/minutes/nov25/1125_voters.pdf

Review of voters in peril

Please https://www.ieee802.org/3/minutes/nov25/1125_peril.pdf

Review of Potential voters

Please see https://www.ieee802.org/3/minutes/nov25/1125_potential.pdf

There were no requests for voting rights during the closing plenary

IEEE 802 LAN/MAN Standards Committee items

Mr. Law showed the IEEE 802 LMSC report.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=28

Mr. Law noted that Beth wasn't in the room and he would move the In-Person Collaboration topic later in the agenda once Beth was able to join. There were no objections.

Mr. Law reviewed the IEEE 802.3 Working Group Proposed election procedures for the March 2026 elections.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=30

MOTION #2

Adopt the election rules as shown in 1125_802_3_closing_plenary.pdf

M: Chad Jones

S: John D'Ambrosia

Procedural (> 50%)

Motion Passed by unanimous consent 14-Nov 2025, 13:51 ICT

Other IEEE 802 PARs

Mr. Lusted noted that the PAR comments were submitted by the deadline. Mr. Lusted noted that all comments submitted by IEEE 802.3 were accommodated.

Liaisons

External Liaison request

Mr. Law reviewed the list of IEEE 802.3 Working Group liaisons and draft sharing coordination list.

https://www.ieee802.org/3/minutes/nov25/1125_802_3_closing_plenary.pdf#page=37

External Liaison letters (new)

ITU-T SG15 Updates to ANT and HNT Standards Overviews and Work Plans [liaison letter](#)

ITU-T SG15 Update to OTNT Standards Overview and Work Plan [liaison letter](#) and [attachment](#)

ITU-T SG15 Development of weakly-coupled multi-core fibre Recommendations [liaison letter](#)

ITU-T SG15 ETCC, 800G in G.698.2 and new B1T applications [liaison letter](#) and attachment [1](#) and [2](#)

ITU-T SG15 Approval of Technical Report on International Optical Networks towards 2030

(ION-2030) and Beyond [liaison letter](#) and [attachment](#)

ITU-T SG15 Technical report of use cases and requirements beyond 10Gbps [liaison letter](#)

OIF: Next Generation CEI-448G Framework document project [liaison letter](#) and [attachment](#)

Mr. Law reminded attendees to log their attendance in IMAT. He asked if there was anyone that was unable to sign into IMAT. There was no response.

Future Meetings Report – Chad Jones

https://www.ieee802.org/3/minutes/nov25/1125_802d3_future_meetings.pdf

Future Meetings Straw Poll:

How many people would like to come back to this venue?

Yes: 61 No: 1

Did you go to the social?

Yes: 62 No: 11

If you attended the social, did you like the social?

Yes: 53 No: 4

Closing reports and actions:

IEEE 802.3 Rules - Adam Healey

https://www.ieee802.org/3/minutes/nov25/1125_rules_close_report.pdf

MOTION #3

Approve the proposed IEEE 802.3 rules change 1-07/25 without a 30-day WG letter ballot.

M: A. Healey S: Kent Lusted

By Rule $\geq 75\%$

Motion Passed by unanimous consent 14-Nov 2025, 14:14 ICT

IEEE 802.3 Maintenance - Adam Healey

https://www.ieee802.org/3/minutes/nov25/1125_maint_close_report.pdf

MOTION #4

Approve the IEEE P802.3 (IEEE 802.3du) Revision to IEEE Std 802.3-2022 PAR in <https://mentor.ieee.org/802-ec/dcn/25/ec-25-0234-02-LMSC-draft-ieee-p802-3-ieee-802-3du-par.pdf>

M: A. Healey S: K. Lusted

Technical $\geq 75\%$

Yes: 106 No: 0 Abstain: 5

Motion Passed 14-Nov 2025, 14:24 ICT

IEEE P802.3da 10 Mb/s Single Pair Multidrop Segments Enhancement Task Force - Chad Jones

https://www.ieee802.org/3/minutes/nov25/1125_802d3da_task_force_close_report.pdf

MOTION #5

Move that the IEEE 802.3 Working Group re-affirm the CSD responses in <https://mentor.ieee.org/802-ec/dcn/20/ec-20-0096-00-ACSD-p802-3da.pdf> and request conditional approval to progress the IEEE P802.3da draft to RevCom once the IEEE Standards Association ballot process has been successfully completed.

M: Chad Jones S: George Zimmerman

Technical $\geq$ 75%

Yes: 96 No: 0 Abstain: 7

Motion Passed 14-Nov 2025, 14:31 ICT

MOTION #6

Move to approve sharing IEEE P802.3da drafts with ISO/IEC JTC 1 SC 25/WG 3 and TIA TR-42 at the discretion of the Task Force Chair.

M: Chad Jones S: George Zimmerman

Technical $\geq$ 75%

Motion Passed by unanimous consent 14-Nov 2025, 14:38 ICT

IEEE P802.3dg 100 Mb/s Long-Reach Single Pair Ethernet Task Force - George Zimmerman

https://www.ieee802.org/3/minutes/nov25/802d3dg_close_report_Nov2025.pdf

MOTION #7

Move to approve sharing IEEE P802.3dg drafts with ISO/IEC JTC 1 SC 25/WG 3, TIA TR-42, and PROFIBUS & PROFINET International (PI) Joint Working Group - Independent Protocol Physical Layer at the discretion of the Task Force Chair.

M: George Zimmerman S: Val Maguire

Technical $\geq$ 75%

Motion Passed by unanimous consent 14-Nov 2025, 15:42 ICT

Mr. Law asked if there was any objection to allowing Mr. Zimmerman to add a plan for SA ballot after the vote today, none responded.

MOTION #8

Move to re-affirm the CSD responses in <https://mentor.ieee.org/802-ec/dcn/22/ec-22-0086-00-ACSD-p802-3dg.pdf> and request conditional approval to progress the IEEE P802.3dg draft to IEEE Standards Association ballot once the Working Group ballot process has been successfully completed

M: George Zimmerman on behalf of the Task Force

Technical ($\geq 75\%$)

Yes: 98 No: 0 Abstain: 4

Motion Passed 14-Nov 2025, 14:46 ICT

IEEE P802.3dj 200 Gb/s, 400 Gb/s, 800 Gb/s, and 1.6 Tb/s Ethernet Task Force closing report – John D'Ambrosia

https://www.ieee802.org/3/minutes/nov25/2511_3dj_closed_report.pdf

MOTION #9

Move that the IEEE 802.3 Working Group approve:

IEEE_802d3_to_ITU_01b_3dj_2511_draft_Redacted.pdf

with editorial license granted to the Chair (or his appointed agent) as liaison communications from the IEEE 802.3 Working Group to ITU

M: John D'Ambrosia

S: Kent Lusted

Technical ($\geq 75\%$)

Y: 98 N: 0 A: 4

Motion Passed 14-Nov 2025, 14:50 ICT

MOTION #10

Move that the IEEE 802.3 Working Group approve:

dambrosia_3dj_01_2511_draft_Redacted.pdf

with editorial license granted to the Chair (or his appointed agent) as liaison communications from the IEEE 802.3 Working Group to ITU, OIF, INCITS, UALink, UEC

M: John D'Ambrosia

S: Kent Lusted

Technical ($\geq 75\%$)

Y: 98 N: 0 A: 1

Motion Passed 14-Nov 2025, 14:59 ICT

IEEE P802.3dk Greater than 50 Gb/s Bidirectional Optical Access PHYs Task Force -Yuanqiu Luo

https://www.ieee802.org/3/minutes/nov25/802d3dk_Task_Force_close_report.pdf

MOTION #11

Move that the IEEE 802.3 Working Group conditionally approve to progress the IEEE P802.3dk draft to RevCom once the IEEE Standards Association ballot process has been successfully completed.

M: Yuanqiu Luo

S: Tamoo Takahara

Technical ($\geq 75\%$)

Y: 94 N: 0 A: 4

Motion Passed 14-Nov 2025, 15:06 ICT

IEEE P802.3dm Asymmetrical Electrical Automotive Ethernet – Natalie Wienckowski

https://www.ieee802.org/3/minutes/nov25/802d3dm_TF_close_report.pdf

The Working Group took a break at 15:12 ICT

The group resumed at 15:34 ICT

Beth Kochuparambil reviewed the In-Person Collaboration slides:

<https://mentor.ieee.org/802-ec/dcn/25/ec-25-0258-01-LMSC-wg-polls-on-voting-changes.pptx>

In-Person collaboration straw polls:

1. For this plenary, I am... (138 voted)
 - A. On-site/in-person (89)
 - B. Remote (49)
2. I support the statement, “In-person attendance is richer and adds value to the standards development process.”
 - A. Yes (109)
 - B. No (29)
3. I believe that a working group voter should, at some point, attend a WG session in person.
 - A. Yes (100)
 - B. No (38)
4. I support the rules change direction of
 - A. requiring in-person attendance to gain and/or maintain voting rights. (46)
 - B. casting votes in person, but hearing opinions and contributions remotely is still allowed. (3)
 - C. both A & B. This returns to pre-covid-like rules, with the added hybrid participation for discussion and contributions. (25)
 - D. no change. Continue to allow gaining/maintaining voting rights and casting votes remotely. (64)

Mr. Law reminded attendees to log their attendance in IMAT. He asked if there was anyone that was unable to sign into IMAT. There was no response.

Mr. Law requested that the polling tool remain open until 17:00 ICT to allow the agenda to continue while providing more time for participants to submit detailed information in their in-person collaboration straw poll responses.

IEEE Std 802.3-2022/Cor 2 (IEEE 802.3dr) – Luisma Torres

https://www.ieee802.org/3/minutes/nov25/802d3dr_task_force_closing_report_01_1125.pdf

MOTION #12

Move that the IEEE 802.3 Working Group progress the IEEE P802.3dr draft 2.0 to Working Group ballot.

M: Luisma Torres on behalf of the Task Force

Technical ($\geq 75\%$)

Motion Passed by unanimous consent 14-Nov 2025, 16:44 ICT

https://www.ieee802.org/3/minutes/nov25/802d3_closing_study_group_report_200GMMF_2511.pdf

MOTION #13

Move that the IEEE 802.3 Working Group approve the IEEE P802.3ds 200 Gb/s per Wavelength MMF PHYs PAR, in <https://mentor.ieee.org/802-ec/dcn/25/ec-25-0216-02-LMSC-draft-ieee-p802-3ds-par.pdf>

M: Mabud Choudhury

S: Guangcan Mi

Technical ($\geq 75\%$)

Y: 95 N: 0 A: 3

Motion Passed 14-Nov 2025, 16:53 ICT

MOTION #14

Move that the IEEE 802.3 Working Group approve the IEEE P802.3ds 200 Gb/s per Wavelength MMF PHYs CSD “Managed Objects”, “Coexistence”, “Broad Market Potential”, “Compatibility”, “Distinct Identity”, “Technical Feasibility”, and “Economic Feasibility” responses, as per <https://mentor.ieee.org/802-ec/dcn/25/ec-25-0217-02-LMSC-draft-ieee-p802-3ds-csd.pdf>

M: Mabud Choudhury

S: Roberto Rodes

Technical ($\geq 75\%$)

Y: 90 N: 0 A: 1

Motion Passed 14-Nov 2025, 16:58 ICT

MOTION #15

Move that the IEEE 802.3 Working Group approve the IEEE P802.3ds 200 Gb/s per Wavelength MMF PHYs objectives, as per https://ieee802.org/3/200GMMF/objectives_200gmmf_01_250917.pdf

M: Mabud Choudhury

S: Eric Bernier

Technical ($\geq 75\%$)

Motion Passed by unanimous consent 14-Nov 2025, 17:00 ICT

MOTION #16

Move that the IEEE 802.3 Working Group request 1st rechartering of IEEE 802.3 200 Gb/s per Wavelength MMF PHYs Study Group

M: Mabud Choudhury on behalf of the study group

By Rule (>50%)

Y: 84 N: 0 A: 1

Motion Passed 14-Nov 2025, 17:02 ICT

Mr. Law noted that should the IEEE P802.3ds project be approved he would be appointing Mabud Choudhury as the Task Force Chair.

Mr. Law asked Ms. Kochuparambil to close the In-Person straw polls and give the results which were added to the straw poll list above.

IEEE 802.3: Ethernet Metadata Services Study Group – David Ofelt

<https://www.ieee802.org/3/minutes/nov25/2025-11-ems-plenary-closing-report.pdf>

MOTION #17

Move that the IEEE 802.3 Working Group approve the IEEE P802.3dt Ethernet Metadata Services PAR, in <https://mentor.ieee.org/802-ec/dcn/25/ec-25-0218-01-LMSC-draft-ieee-p802-3dt-par.pdf>

M: David Ofelt

S: Gary Nicholl

Technical ($\geq 75\%$)

Y: 81 N: 0 A: 2

Motion Passed 14-Nov 2025, 17:15 ICT

MOTION #18

Move that the IEEE 802.3 Working Group approve the IEEE P802.3dt Ethernet Metadata Services CSD “Managed Objects”, “Coexistence”, “Broad Market Potential”, “Compatibility”, “Distinct Identity”, “Technical Feasibility”, and “Economic Feasibility” responses, as per <https://mentor.ieee.org/802-ec/dcn/25/ec-25-0219-01-LMSC-draft-ieee-p802-3dt-csd.pdf>

M: David Ofelt

S: Gary Nicholl

Technical ($\geq 75\%$)

Y: 83 N: 0 A: 4

Motion Passed 14-Nov 2025, 17:18 ICT

MOTION #19

Move that the IEEE 802.3 Working Group approve the IEEE P802.3dt Ethernet Metadata Services objectives, as per https://www.ieee802.org/3/EMS/projdoc/objectives_ems_251022.pdf

M: David Ofelt

S: Gary Nicholl

Technical ($\geq 75\%$)

Motion Passed by unanimous consent 14-Nov 2025, 17:20 ICT

MOTION #20

Move that the IEEE 802.3 Working Group request 1st rechartering of IEEE 802.3 Ethernet Metadata Services Study Group

M: David Ofelt on behalf of the Study Group

By rule ($> 50\%$)

Y: 79 N: 0 A: 4

Motion Passed 14-Nov 2025, 17:21 ICT

Mr. Law noted that should the IEEE P802.3dt project be approved he would be appointing David Ofelt as the Task Force Chair.

IEEE 802.3 New Ethernet Applications ad hoc – Jon Lewis

https://www.ieee802.org/3/minutes/nov25/1125_NEA_close_report.pdf

MOTION #21

Move that the IEEE 802.3 Working Group approve:

IEEE_802d3_to_UEC_SNIA_OIF_UAL_ITU_FC_EA_OCP_e4ai_2511_draft_Redacted.pdf

with editorial license granted to the Chair (or his appointed agent) as liaison communications from the IEEE 802.3 Working Group to UEC, SNIA, OIF, UALink, ITU-T, INCITS Fibre Channel, Ethernet Alliance, Open Compute Project Foundation

M: John D'Ambrosia

S: Kent Lusted

Technical ($\geq 75\%$)

Y: 74 N: 0 A: 2

Motion Passed 14-Nov 2025, 17:32 ICT

MOTION #22

Move that the IEEE 802.3 Working Group approve:

IEEE_802d3_to_ITU_IEC_e4ai_2511_draft_Redacted.pdf

with editorial license granted to the Chair (or his appointed agent) as liaison communications from the IEEE 802.3 Working Group to ITU and IEC

M: John D'Ambrosia

S: Kent Lusted

Technical ($\geq 75\%$)

Y: 72 N: 0 A: 3

Motion Passed 14-Nov 2025, 17:38 ICT

MOTION #23

Move to generate COM v4.12 from COM 4.11 and the dispositions per 1125_COM_ad_hoc_plenary_close_report, slide3.

M: Kent Lusted

S: Howard Heck

Technical ($\geq 75\%$)

Motion Passed by unanimous consent 14-Nov 2025, 17:44 ICT

MOTION #24

Move that the IEEE 802.3 Working Group approve submitting the 802.3 YANG Tier 3 Open Source Project Proposal as per:

802.3 YANG Modules OSCom Tier 3 Project Request document

802.3 YANG Modules OSCom Tier 3 Project Request slides

M: Peter Jones

S: Jason Potterf

By Rule ($\geq 75\%$)

Y: 54 N: 0 A: 9

Motion Passed 14-Nov 2025, 17:48 ICT

Awards:

IEEE Std 802.3.2-2025 YANG Data Model (Revision) – Marek Hajduczenia

Mr. Law asked if there was any additional general business:

Mr. Law announced that as the agenda had been exhausted the meeting was adjourned.

Mr. Law adjourned the meeting at 18:00 ICT.

Adjourned.

Appendix A: Attendance list for Working Group Opening plenary from IMAT

Name	Affiliation	Employer
Ahuja, Ramanjit	ON Semiconductor	ON Semiconductor
Aripirala, Ravi	Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.	
Baggett, Tim	Microchip Technology, Inc.	Microchip Technology, Inc.
Benyamin, Saied	Ethernovia	Ethernovia
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
Beruto, Piergiorgio	onsemi	onsemi
Boyer, Rich	Aptiv Signal and Power Solutions	Aptiv - Signal and Power Solutions
Brooks, Paul	Viavi Solutions	Viavi solutions GmbH
Brown, Matthew	Alphawave Semi	Alphawave Semi
Bruckman, Leon	NVIDIA	NVIDIA
Calvin, John	Keysight Technologies	Keysight Technologies
Castro, Jose	Panduit Corp.	Panduit
Chang, Jae-yong	Keysight Technologies Inc	Keysight Technologies Inc
Chen, Chan	Independent/AOI	Self Employed
cheng, xiaoyue	Infineon Technologies	
Chimento, Nicholas	Analog Devices Inc.	
Chini, Ahmad	Broadcom Corporation	Broadcom Corporation
Choudhury, Golam	Lightera	Lightera
Cole, Christopher R	Coherent Corp.	Finisar Corporation
Cordaro, Jay	Analog Devices	Analog Devices
Dai, Shaoan	Infineon Technologies	
Dalmia, Kamal	NXP Semiconductors	Aviva Links Inc
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	Nvidia	NVIDIA
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.
Donahue, Curtis	Rohde & Schwarz	Rohde & Schwarz
Dudek, Michael	Marvell	Marvell
Effenberger, Frank	Futurewei Technologies	Futurewei Technologies

Name	Affiliation	Employer
El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc
Estes, David	VIAVI Solutions	Spirent Communications
Estrakh, Daniel	Valens Semiconductor	Valens Semiconductor
Fan, Xiaojie	Huawei Technologies Co., Ltd	
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Ganesan, Aravind	Texas Instruments Inc.	Texas Instruments Inc.
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
George, John	Lightera	
Ghiasi, Ali	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.	Ghiasi Quantum LLC
Gilb, James	General Atomics Aeronautical Systems, Inc.	General Atomics Aeronautical Systems, Inc.
Glanzner, Martin	SEI Automotive Europe GmbH	SEI ANTech-Europe GmbH
Goel, Sachin	NXP	Aviva Links Inc
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Goto, Hideki	Toyota Motor Corporation	Toyota Motor Corporation
Graber, Steffen	Pepperl+Fuchs SE	Pepperl+Fuchs SE
Gubow, Martin	Keysight Technologies	Keysight Technologies
Gupta, Ajeya	General Motors Company	
Han, Ruibo	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
HE, MICHAEL	TeraHop Pte. Ltd.	
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics
Hogenmueller, Thomas	Robert Bosch GmbH	Robert Bosch GmbH
Hong, Paul	MaxLinear, Inc	
Houck, TJ	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huang, Michael	Berxel Photonics	

Name	Affiliation	Employer
Huber, Thomas	Nokia	Nokia
Hutchison, Guy	Aviva Links Inc; Aviva Links Inc.	Aviva Links
HYAKUTAKE, YASUHIRO	Orbray Co., Ltd.	Orbray Co., Ltd.
Isono, Hideki	Furukawa FITEL Optical Components	Furukawa FITEL Optical Components Limited
Issenhuth, Tom	Huawei Technologies Co., Ltd	Issenhuth Consulting, LLC
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD
Jeffreis, Brad	Analog Devices Inc.	
Jin, Robert	Montage Technology	Montage Technology, Inc
Jochim, Markus	General Motors Company	General Motors Company
Johnson, John	Broadcom Corporation	Broadcom Corporation
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Jonsson, Ragnar	Marvell	Marvell Semiconductor, Inc.
Kabra, Lokesh	Synopsys, Inc.	Synopsys, Inc.
Kagami, Manabu	Nagoya Institute of Technology (NITech)	Nagoya Institute of Technology
Kandarpa, Venkata	Aviva Links Inc; Aviva Links Inc.	Chelsio Communications
Kanno, Atsushi	Nagoya Institute of Technology	Nagoya Institute of Technology
Kapoor, Samay	Aviva Links Inc.	Aviva Links
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
KATO, TAKAHIRTO	Dexterials	
KAWAHARA, TATSUMASA	Murata Manufacturing Co., Ltd.	
Kikuta, Tomohiro	Orbray Co., Ltd.	Orbray Co., Ltd.
Kim, Do Kyun	LG ELECTRONICS	
Kim, Gyudong	Analog Devices Inc.	Analog Devices Inc.
Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.
Kim, Yongbum	General Motors Company	General Motors Company
Kimber, Eric	Semtech Ltd	Semtech Ltd
Kleinwaechter, Mathias	in-tech GmbH	in-tech GmbH
Koch, Lavi	Lavi Koch Nvidia	
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.

Name	Affiliation	Employer
Kock, Joerg	NXP Semiconductors	NXP Semiconductors
Kocsis, Sam	Amphenol Corporation	Amphenol Corporation
Kondo, Taiji	Dexterials Corporation	Dexterials Corporation
Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Kotani, Yasuhiro	DENSO	DENSO
Kutscher, Noam	Marvell	
Lackner, Hans	QoSCom GmbH	QoSCom GmbH
Lambert, Angela	Corning Incorporated	Corning Incorporated
Lasry, Ariel	Qualcomm Technologies, Inc	Qualcomm Technologies, Inc
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise
Lee, Ching-Yen	Realtek Semiconductor Corp.	
Lessard, Stephane	Ericsson AB	
Lewis, David	SPECIPHY, LUMENTUM	SPECIPHY
Lewis, Jon	Dell Technologies	Dell Technologies
Li, Mike-Peng	Intel	Altera Corporation
Lieder, Eyal	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Lim, Hoei	NXP Semiconductors	Aviva Links
Lin, YK	Realtek Semiconductor Corp.	
Lin, Youxi	Huawei Technologies Co., Ltd	Huawei Technologies Duesseldorf GmbH
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Lo, William	Axonne Inc.	Axonne Inc.
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Maguire, Valerie	Copperopolis (affl with CME Consulting, Cisco, Dell, ADI, MCHP, and NXP)	Copperopolis
Maki, Jeffery	Hewlett Packard Enterprise	Juniper Networks, Inc.
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Mark, Simon	Wurth Elektronik Group	Wurth Elektronik Group
Marques, Flavio	Lightera	Lightera
Martino, Kjersti	Inneos	Inneos
Mascitto, Marco	Nokia	Infinera Canada Inc.

Name	Affiliation	Employer
Matheus, Kirsten	BMW Group	BMW Group, VDA
McClellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Mellitz, Richard	Samtec, Inc.	Samtec, Inc.
mi, guangcan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Miskho, Michael	Analog Devices Inc.	
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Muhigana, Ernest	Macom Technology Solutions Inc	MACOM Technology Solutions Holdings, Inc.
Muller, Shimon	Enfabrica	Enfabrica Corp.
Muma, Scott	Microchip Technology, Inc.	
MURAKAMI, YUKI	lFinity	lFinity
Murray, Brian	Analog Devices Inc.	Analog Devices Inc.
Murty, Ramana	Broadcom Corporation	Broadcom Inc.
Nagaraja, Srikanth	Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.	
Nakamoto, Edward	VIAVI Solutions	Spirent Communications
Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Ng, Hiok Tiaq	NXP Semiconductors	NXP Semiconductors
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
NIIHARA, YOSHIHIRO	Fujikura Ltd.	Fujikura Ltd.
Ninomiya, Tiger	Accelink USA Corporation	Accelink USA Corporation
Noujeim, Leesa	Google	Google
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Juniper Networks, Inc.
OGAWA, SHOJI	FURUKAWA ELECTRIC	Furukawa
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Pal, Debajyoti	ON Semiconductor	
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.
Pan, Chunpo	Broadcom Corporation	
Pandey, Sujan	NXP Semiconductors	Velinktech

Name	Affiliation	Employer
Parkholm, Ulf	Ericsson AB	Telefon AB LM Ericsson
peng, semmy	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Pfeifle, Joerg	Keysight Technologies	Keysight Technologies
Pineda, Luis	LP Tech Advisors, LLC (Samsung; Ethernovia)	LP Tech Advisors, LLC
Potterf, Jason	Cisco Systems, Inc.	Cisco Systems, Inc.
Quan, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Rajagopal, Karthik	Texas Instruments Inc.	
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Razavi, Alireza	Infineon Technologies	Marvell
Regev, Alon	Keysight Technologies	Keysight Technologies
Reinhard, Michael	SEI Automotive Europe GmbH	SEI Automotive Europe GmbH
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rock, Jason	Dell Inc.; Dell Technologies	Dell Inc.
Rodes, Roberto	II-VI	II-VI
Royer, Tyler	SENKO Advanced Components	SENKO Advanced Components
Rysin, Alexander	NVIDIA	NVIDIA
Sakai, Toshiaki	socionext	Socionext Inc.
Sambasivan, Sam	AT&T	AT&T
Schedl, Anton	BMW Group	BMW Group
Sedarat, Hossein	Ethernovia	Ethernovia
Sekel, Steve	wilder Technologoeis	Wilder Technologies
SETH, SUMANTRA	Texas Instruments Inc.	Texas Instruments Inc.
Shah, Anup	Siemens EDA	Siemens Corporation
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
shirani, ramini	Aquantia	Ethernovia
Sommers, Scott	Molex Incorporated	Molex LLC
Son, Yung Sung	Optomind Inc	Optomind Inc
Spruit, Hans	TRUMPF	TRUMPF
Sriram, Chandrasekhar	Texas Instruments Inc.	

Name	Affiliation	Employer
Srivastava, Atul	NTT Electronics	NEL-America
Strohmeier, Heiko	Robert Bosch GmbH	Robert Bosch GmbH
Sun, jingcong	Motorcomm Electronic Technology Co	Motorcomm Electronic Technology Co
Sun, Yi	Lightera	Lightera
Swenson, Norman	Norman Swenson Consulting; Point2 Technology Inc.; Nokia	Norman Swenson Consulting
TAKAHARA, TOMOO	1FINITY	FUJITSU LABORATORIES LIMITED
TAKEUCHI, JUNICHI	JAE Electronics, Inc.	JAE Electronics, Inc
Tan, Kan	Tektronix, Inc.	Tektronix, Inc.
TAN, SISI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Tan, Yuxuan	Motorcomm	Motorcomm
Tanc, Ahmet	NXP Semiconductors; NXP Semiconductors	
TAZEBAY, MEHMET	Broadcom Corporation	Broadcom Corporation
Theodoras, James	Scintil Photonics	Scintil Photonics
Thompson, Geoffrey	INDEPENDENT	GraCaSI S.A.
tian, yuchi	China Mobile	
Torres, Luisma	KD	Knowledge Development for POF SL
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Tu, Mike	Broadcom Corporation	Broadcom Corporation
Turner, Max	Ethernovia	Ethernovia
Vakilian, Kambiz	Broadcom Corporation	Broadcom Corporation
Val, Inaki	MaxLinear, Inc.	MaxLinear, Inc.
Veloso Cauce, Gumersindo	BMW AG; BMW Group	BMW Group
Wang, Haojie	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Shun-Sheng	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.
WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Weaver, James	Arista Networks	Arista Networks

Name	Affiliation	Employer
Wei, Terry	Analog Devices Inc.	
Welch, Brian	Luxtera	Cisco Systems, Inc.
Wienckowski, Natalie	IVN Solutions LLC; Ethernovia	IVN Solutions LLC
Wingrove, Michael	Ciena Corporation	Ciena Corporation
Wu, Dance	Infineon Technologies	Marvell Semiconductor, Inc.
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
xu, wenxiong	HG Genuine	HG Genuine
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Zerna, Conrad	NXP Semiconductors	Aviva Links Inc
Zhang, Tingting	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhang, Wei	Broadcom Corporation	
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zimmerman, George	CME Consulting/Analog Devices, APL Group, Cisco, Infineon, OnSemi, Sony	CME Consulting, Inc.
Zivny, Pavel	MultiLane	MultiLane
Zuo, Mingqing	China Mobile Research Institute	

Appendix B: Attendance list for Working Group Closing plenary from IMAT

Name	Affiliation	Employer
Ahuja, Ramanjit	ON Semiconductor	ON Semiconductor
Akinwale, Oluwafemi	Intel Corporation	Intel Corporation
Aripirala, Ravi	Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.	
Benyamin, Saied	Ethernovia	Ethernovia
Bernier, Eric	Huawei Technologies Canada Co., Ltd.	Huawei Technologies Canada Co., Ltd.
Beruto, Piergiorgio	onsemi	onsemi
Brooks, Paul	Viavi Solutions	Viavi solutions GmbH
Brown, Matthew	Alphawave Semi	Alphawave Semi
Bruckman, Leon	NVIDIA	NVIDIA
Calvin, John	Keysight Technologies	Keysight Technologies
Castro, Jose	Panduit Corp.	Panduit
Chang, Jae-yong	Keysight Technologies Inc	Keysight Technologies Inc
Chen, Chan	Independent/AOI	Self Employed
cheng, xiaoyue	Infineon Technologies	
Chimento, Nicholas	Analog Devices Inc.	
Chini, Ahmad	Broadcom Corporation	Broadcom Corporation
Choudhury, Golam	Lightera	Lightera
Cox, Ian	Broadcom Corporation	
Dai, Shaoan	Infineon Technologies	
Dalmia, Kamal	NXP Semiconductors	Aviva Links Inc
D'Ambrosia, John	Futurewei Technologies, U.S. Subsidiary of Huawei	Futurewei Technologies, U.S. Subsidiary of Huawei
Dawe, Piers J G	Nvidia	NVIDIA
de Koos, Andras	Microchip Technology Inc	Microchip Technology Inc
Dinh, Thuyen	Pulse Electronics	Pulse Electronics
Djahanshahi, Hormoz	Microchip Technology, Inc.	Microchip Technology, Inc.
Donahue, Curtis	Rohde & Schwarz	Rohde & Schwarz
Dsilva, Hansel	Amphenol Corporation	
Dudek, Michael	Marvell	Marvell
Effenberger, Frank	Futurewei Technologies	Futurewei Technologies

El-Chayeb, Ahmad	Keysight Technologies Inc	Keysight Technologies Inc
Estes, David	VIAVI Solutions	Spirent Communications
Estrakh, Daniel	Valens Semiconductor	Valens Semiconductor
Fan, Xiaojie	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Fan, Xiaojie	Huawei Technologies Co., Ltd	
Ferretti, Vincent	Corning Incorporated	Corning Incorporated
Galan, Jose	MaxLinear, Inc.	MaxLinear, Inc.
Ganesan, Aravind	Texas Instruments Inc.	Texas Instruments Inc.
Geng, Limin	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Ghiasi, Ali	Ghiasi Quantum LLC; Marvell Semiconductor, Inc.	Ghiasi Quantum LLC
Glanzner, Martin	SEI Automotive Europe GmbH	SEI ANTech-Europe GmbH
Goel, Sachin	NXP	Aviva Links Inc
Gorshe, Steven Scott	Microchip Technology, Inc.	Microchip Technology, Inc.
Goto, Hideki	Toyota Motor Corporation	Toyota Motor Corporation
Graber, Steffen	Pepperl+Fuchs SE	Pepperl+Fuchs SE
Gubow, Martin	Keysight Technologies	Keysight Technologies
Han, Ruibo	China Mobile Communications Corporation (CMCC)	China Mobile Communications Corporation (CMCC)
HE, MICHAEL	TeraHop Pte. Ltd.	
He, Xiang	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Healey, Adam	Broadcom Inc.	Broadcom Inc.
Heck, Howard	TE Connectivity	TE Connectivity
Hidaka, Yasuo	Credo Semiconductor	Credo Semiconductor
Hiroaki, Kukita	Yamaichi Electronics	Yamaichi Electronics
Hogenmueller, Thomas	Robert Bosch GmbH	Robert Bosch GmbH
Hong, Paul	MaxLinear, Inc	
Huang, Kechao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Huber, Thomas	Nokia	Nokia
HYAKUTAKE, YASUHIRO	Orbray Co., Ltd.	Orbray Co., Ltd.
Isono, Hideki	Furukawa FITEL Optical Components	Furukawa FITEL Optical Components Limited
Issenhuth, Tom	Huawei Technologies Co., Ltd	Issenhuth Consulting, LLC
Jackson, Kenneth	Sumitomo Electric Industries, LTD	Sumitomo Electric Industries, LTD

Jeffreis, Brad	Analog Devices Inc.	
Jin, Robert	Montage Technology	Montage Technology, Inc
Jochim, Markus	General Motors Company	General Motors Company
Johnson, John	Broadcom Corporation	Broadcom Corporation
Jones, Chad	Cisco Systems, Inc.	Cisco Systems, Inc.
Jones, Peter	Cisco Systems, Inc.	Cisco Systems, Inc.
Jonsson, Ragnar	Marvell	Marvell Semiconductor, Inc.
Kabra, Lokesh	Synopsys, Inc.	Synopsys, Inc.
Kagami, Manabu	Nagoya Institute of Technology (NITech)	Nagoya Institute of Technology
Kandarpa, Venkata	Aviva Links Inc; Aviva Links Inc.	Chelsio Communications
Kanno, Atsushi	Nagoya Institute of Technology	Nagoya Institute of Technology
Kapoor, Samay	Aviva Links Inc.	Aviva Links
Kareti, Upen	Cisco Systems, Inc.	Cisco Systems, Inc.
KATO, TAKAHIRTO	Dexerials	
KAWAHARA, TATSUMASA	Murata Manufacturing Co., Ltd.	
Kikuta, Tomohiro	Orbray Co., Ltd.	Orbray Co., Ltd.
Kim, Do Kyun	LG ELECTRONICS	
Kim, Gyudong	Analog Devices Inc.	Analog Devices Inc.
Kim, Kihong/Joshua	Hirose Electric (USA), Inc.	Hirose Electric (USA), Inc.
Kim, Yongbum	General Motors Company	General Motors Company
Kimber, Eric	Semtech Ltd	Semtech Ltd
Kleinwaechter, Mathias	in-tech GmbH	in-tech GmbH
Kochuparambil, Elizabeth	Cisco Systems, Inc.	Cisco Systems, Inc.
Kondo, Taiji	Dexerials Corporation	Dexerials Corporation
Kota, Kishore	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Kotani, Yasuhiro	DENSO	DENSO
Kutscher, Noam	Marvell	
Lackner, Hans	QoSCom GmbH	QoSCom GmbH
Lambert, Angela	Corning Incorporated	Corning Incorporated
Landry, Gary	Texas Instruments Inc.	Texas Instruments Inc.
Lasry, Ariel	Qualcomm Technologies, Inc	Qualcomm Technologies, Inc
Law, David	Hewlett Packard Enterprise	Hewlett Packard Enterprise

Lee, Ching-Yen	Realtek Semiconductor Corp.	
Lessard, Stephane	Ericsson AB	
Lewis, Jon	Dell Technologies	Dell Technologies
Lim, Hoei	NXP Semiconductors	Aviva Links
Lin, YK	Realtek Semiconductor Corp.	
Lin, Youxi	Huawei Technologies Co., Ltd	Huawei Technologies Duesseldorf GmbH
Little, Terrance	Foxconn Electronics Inc.	Foxconn Electronics Inc.
Liu, Cathy	Broadcom Corporation	Broadcom Corporation
Lo, William	Axonne Inc.	Axonne Inc.
Luo, Yuanqiu	Futurewei Technologies	Futurewei Technologies
Lusted, Kent	Synopsys, Inc.	Synopsys, Inc.
Maguire, Valerie	Copperopolis (aff'l with CME Consulting, Cisco, Dell, ADI, MCHP, and NXP)	Copperopolis
Maki, Jeffery	Hewlett Packard Enterprise	Juniper Networks, Inc.
Maniloff, Eric	Ciena Corporation	Ciena Corporation
Mark, Simon	Wurth Elektronik Group	Wurth Elektronik Group
Marques, Flavio	Lightera	Lightera
Martino, Kjersti	Inneos	Inneos
Mascitto, Marco	Nokia	Infinera Canada Inc.
McClellan, Brett	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
mi, guangan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Miskho, Michael	Analog Devices Inc.	
Moorwood, Charles	Keysight Technologies	Keysight Technologies
Muhigana, Ernest	Macom Technology Solutions Inc	MACOM Technology Solutions Holdings, Inc.
Muller, Shimon	Enfabrica	Enfabrica Corp.
Muma, Scott	Microchip Technology, Inc.	
MURAKAMI, YUKI	1Finity	1Finity
Murray, Brian	Analog Devices Inc.	Analog Devices Inc.
Nagaraja, Srikanth	Texas Instruments (India) Pvt. Ltd.; Texas Instruments Inc.	
Nakamoto, Edward	VIAVI Solutions	Spirent Communications

Nering, Raymond	Cisco Systems, Inc.	Cisco Systems, Inc.
Ng, Hiok Tiaq	NXP Semiconductors	NXP Semiconductors
Nicholl, Gary	Cisco Systems, Inc.	Cisco Systems, Inc.
Nicholl, Shawn	Advanced Micro Devices (AMD)	Advanced Micro Devices (AMD)
NIIHARA, YOSHIHIRO	Fujikura Ltd.	Fujikura Ltd.
Ninomiya, Tiger	Accelink USA Corporation	Accelink USA Corporation
Noujeim, Leesa	Google	Google
Nowell, Mark	Cisco Systems, Inc.	Cisco Systems, Inc.
Ofelt, David	Hewlett Packard Enterprise	Juniper Networks, Inc.
OGAWA, SHOJI	FURUKAWA ELECTRIC	Furukawa
Omori, Kumi	NEC Corporation	NEC Corporation
Opsasnick, Eugene	Broadcom Inc.	Broadcom Inc.
Pal, Debajyoti	ON Semiconductor	
Palkert, Thomas	Samtec, Inc.	Samtec, Inc.
Pan, Chunpo	Broadcom Corporation	
Pandey, Sujan	NXP Semiconductors	Velinktech
Parkholm, Ulf	Ericsson AB	Telefon AB LM Ericsson
peng, semmy	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Pepper, Gerald	Keysight Technologies	Keysight Technologies
Pfeifle, Joerg	Keysight Technologies	Keysight Technologies
Pineda, Luis	LP Tech Advisors, LLC (Samsung; Ethernovia)	LP Tech Advisors, LLC
Potterf, Jason	Cisco Systems, Inc.	Cisco Systems, Inc.
Quan, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rabinovich, Rick	Keysight Technologies	Keysight Technologies
Ran, Adee	Cisco Systems, Inc.	Cisco Systems, Inc.
Razavi, Alireza	Infineon Technologies	Marvell
Reinhard, Michael	SEI Automotive Europe GmbH	SEI Automotive Europe GmbH
Ren, Hao	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Rock, Jason	Dell Inc.; Dell Technologies	Dell Inc.
Rodes, Roberto	II-VI	II-VI
Royer, Tyler	SENKO Advanced Components	SENKO Advanced Components
Rysin, Alexander	NVIDIA	NVIDIA

Sakai, Toshiaki	socionext	Socionext Inc.
Schedl, Anton	BMW Group	BMW Group
Sekel, Steve	wilder Technologoeis	Wilder Technologies
SETH, SUMANTRA	Texas Instruments Inc.	Texas Instruments Inc.
Shah, Anup	Siemens EDA	Siemens Corporation
Sharma, Rohit	Molex Incorporated	
Sheffi, Nir	Alphawave	Alphawave
Shiino, Masato	FURUKAWA ELECTRIC	FURUKAWA ELECTRIC
shirani, ramini	Aquantia	Ethernovia
Shrikhande, Kapil	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
Sommers, Scott	Molex Incorporated	Molex LLC
Son, Yung Sung	Optomind Inc	Optomind Inc
Spruit, Hans	TRUMPF	TRUMPF
Sriram, Chandrasekhar	Texas Instruments Inc.	
Srivastava, Atul	NTT Electronics	NEL-America
Strohmeier, Heiko	Robert Bosch GmbH	Robert Bosch GmbH
Sun, jingcong	Motorcomm Electronic Technology Co	Motorcomm Electronic Technology Co
Swenson, Norman	Norman Swenson Consulting; Point2 Technology Inc.; Nokia	Norman Swenson Consulting
TAKAHARA, TOMOO	1FINITY	FUJITSU LABORATORIES LIMITED
TAKEUCHI, JUNICHI	JAE Electronics, Inc.	JAE Electronics, Inc
TAN, SISI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Tan, Yuxuan	Motorcomm	Motorcomm
Theodoras, James	Scintil Photonics	Scintil Photonics
Thompson, Geoffrey	INDEPENDENT	GraCaSI S.A.
tian, yuchi	China Mobile	
Torres, Luisma	KD	Knowledge Development for POF SL
Tracy, Nathan	TE Connectivity	TE Connectivity
Tran, Viet	Keysight Technologies	Keysight Technologies
Tu, Mike	Broadcom Corporation	Broadcom Corporation
Turner, Max	Ethernovia	Ethernovia

Vakilian, Kambiz	Broadcom Corporation	Broadcom Corporation
Val, Inaki	MaxLinear, Inc.	MaxLinear, Inc.
Veloso Cauce, Gumersindo	BMW AG; BMW Group	BMW Group
Wang, Ruoxu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Wang, Shun-Sheng	Realtek Semiconductor Corp.	Realtek Semiconductor Corp.
WANG, Xuebo	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Weaver, James	Arista Networks	Arista Networks
Wei, Terry	Analog Devices Inc.	
Welch, Brian	Luxtera	Cisco Systems, Inc.
Wienckowski, Natalie	IVN Solutions LLC; Ethernovia	IVN Solutions LLC
Wingrove, Michael	Ciena Corporation	Ciena Corporation
Wu, Dance	Infineon Technologies	Marvell Semiconductor, Inc.
Wu, Peter	Marvell Semiconductor, Inc.	Marvell Semiconductor, Inc.
XU, LI	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
xu, wenxiong	HG Genuine	HG Genuine
Xu, Yu	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Yamazaki, Kinya	APRESIA Systems	APRESIA Systems
Zerna, Conrad	NXP Semiconductors	Aviva Links Inc
Zhang, Tingting	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zhang, Wei	Broadcom Corporation	
Zhuang, Yan	Huawei Technologies Co., Ltd	Huawei Technologies Co., Ltd
Zimmerman, George	CME Consulting/Analog Devices, APL Group, Cisco, Infineon, OnSemi, Sony	CME Consulting, Inc.
Zivny, Pavel	MultiLane	MultiLane